

PRODUCT DESCRIPTION

Stress-relieving, heat distributing, decoupling and impact noise reducing board for parquet and multi-layered parquet floors, and for ceramic tiles and natural stone floors. The board is used especially for problematic substrates.

The MULTI-TOP decoupling board is a very low emission laying material (acc. to GEV), breakproof and rot- resistant.

It can be used as decoupling and impact noise reducing board on wall and floor areas indoors under many covering materials (ceramic tiles and natural stone, parquet, as well as multi-layer parquet) for traffic loads of up to 5 kN/m².

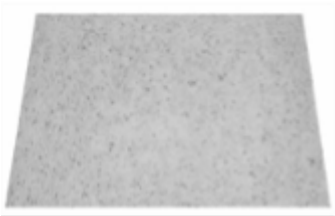
For ceramic tiles and natural stone with a material thickness of less than 10 mm as well as for any covering formats less than 100 x 100 mm, filling is required with a fibre-reinforced filler (min. 3 mm layer thickness). Only the 4 mm board is best suited for use in underfloor heating systems.

Storage:

In a frost-free cool and dry environment on wooden racking in unopened container. Unlimited shelf-life.

Delivery Method:

Item	Container	Outer Packaging	Pallet
4mm	Pcs.	-	200 pcs



PROCESSING

Recommended tools:

Sharp knife or Jigsaw

Processing:

In combination with ceramic coverings and natural stone:

1. Apply RS-BOND flexible adhesive (C2,S1) to the prepared substrate, to give an even bond across the whole board using the application gun or with a TKB B11 notched trowel.
2. Place the MultiTop heat distribution and decoupling board into the adhesive before it has set and tap or rub it in.
3. The MultiTop decoupling boards must be installed without cavities over their entire area.
4. Make sure that no mirroring or cross-joints of the heating board joints occur between layers during installation. Expansion joints should be applied to adjacent ascending structures (incl. edge insulating strips).

5. For ceramic tiles and natural stone with a material thickness of less than 10mm and any covering formats less than 100 x 100 mm, prime and smooth with a fibre-reinforced compound (min. 3mm layer thickness is required).
6. Expansion joints should be applied to the adjacent structures (including edge insulation strips).
7. Lay the surface covering (natural stone or ceramic) in thin-bed process with flexible adhesive mortar for the laying material (C2,S1) according to the local and National rules and codes of practice.
8. Important for noise reduction: There may not be any connection between the joint edges of the individual adjacent MultiTop decoupling boards. Edge insulation strips are to be applied to adjacent structures.

In combination with parquet and laminate floors:

1. Apply RS-BOND flexible adhesive to the prepared base substrate using the application gun or with a TKB B11 trowel.
2. Place the MultiTop heat distribution and decoupling board in the adhesive bed and tap or rub in with a suitable tapping plank.
3. After drying time (product and temperature dependent) of 6-24 hours of the RS-BOND used, apply parquet adhesive of the same system using the application gun or with suitable toothing depending on parquet type (B2,B3,PK) to the MultiTop heat distribution and decoupling board and lay the parquet to be glued.
4. Important for noise reduction: There may not be any connection between the joint edges of the individual adjacent MultiTop decoupling boards. Edge insulation strips are to be applied to adjacent structures.

If being used with vinyl ie an LVT or PVC, then a smoothing compound such as a fibre-reinforced filler will need to be laid over the MultiTop. The thickness and sometimes even the type will need to be specified by the floor finish manufacturer/ supplier to ensure it meets their guarantees and warranties.

TECHNICAL DATA

Property	Cellulose
Colour	White / Grey
Format	1200 x 600 mm
Material thickness	4 mm
Tolerances cut	+/- 1.0 mm thickness +/- 0.5 mm
Weight	approx. 3 kg/m ²
Crack bridging	1.41 mm
Thermal conductivity (DIN 52612)	0.16 (W/mK)
Thermal resistance (DIN 52612)	0.025 (m ² K/W)
Compression strength (EN 826)	590 kN/m ²
Elasticity module (DIN 53547)	699 MN/m ²
Thermal expansion	30 µm/m
Fire class	E (EN 13501) B2 (DIN 4102)
Vapour diffusion current density (WDD)	21.2 g/(m ² xd)
Impact sound improvement* - loose	approx. 13 dB
Impact sound improvement* - tile adhesive	approx. 10 dB
Impact sound improvement* - parquet adhesive	approx. 15 dB
EMICODE class	EC1 PLUS https://www.emicode.com/en/home/
*tested to EN ISO 14-8	

SUBSTRATE

Suitable substrates:

Suitable on all standard substrates (see list below) as well as on old tile and natural stone flooring, adhesive concrete block flooring, mastic asphalt, dry screeds, chipboard, metal, glass etc. on old substrates with adhesive mortar layers as well as on conventional cement and calcium sulphate screeds.

- Concrete
- Cement screed
- Anhydrite screed
- Mastic asphalt
- Gypsum Plaster
- Gypsum plasterboard
- Lime-cement Plaster
- Masonry
- Smooth concrete blocks
- Aerated concrete blocks
- Wooden materials
- Insulation Boards

- Foil Faced Insulation and Wooden Materials

Substrate pre-treatment:

The substrate must be dry, frost-free, solid, weight-bearing, dimensionally stable, free of dust, dirt, oil, grease, release agents and loose parts, and it must comply with the applicable technical National and European directives, standards and “generally accepted rules of the trade”.

The substrate is to be pre-treated according to the relevant current standards, with pre-coatings and smoothing compounds. OMNIE products are specifically designed for pre-treatment. All substrates are to be sanded, wiped, cleaned, vacuumed of all containments.

PRODUCT AND PROCESSING INFORMATION

Material information:

- When working outside the ideal temperature and/or humidity range, the material properties may change significantly – Temper materials accordingly before processing!
- To retain the product properties, no foreign materials may be mixed in!
- Water dosing amounts or thinning specifications must be precisely kept!
- Check coloured products before use for colour accuracy!
- Colour consistency can only be guaranteed within a batch.
- The colouring is significantly influenced by the environmental conditions.

Environmental information:

- Do not process at temperatures below + 5 °C!
- The ideal temperature range for material, substrate and air is +15 °C to +25 °C.
- The ideal relative air humidity range is between 40% to 60%.
- Increased humidity and/or lower temperatures delay, lower air humidity and/or higher temperatures accelerate drying, setting and hardening.
- Ensure sufficient ventilation during the drying, reaction and hardening phase; avoid draughts!
- Protect from direct sunlight, wind and weather!
- Protect adjacent components!

Tips:

- We recommend using a test surface first or a small area for initial, small-scale testing.
- Observe the product data sheets of all OMNIE products used in the system.
- Keep a genuine original container of the respective batch for later repair work.

The information provided reflects average values that were obtained under laboratory conditions. Due to the use of natural raw materials, the indicated values of individual deliveries may vary slightly without impacting the product suitability.

SAFETY INSTRUCTIONS

This leaflet is based on extensive experience, is intended to convey the best of our knowledge, is not legally binding and does neither constitute a contractual legal relationship nor a subsidiary obligation resulting from the bill of sale.

The quality of our materials is guaranteed within the framework of our general terms and conditions. Our products may be used by professionals and/or experienced and accordingly technically skilled persons only. Users are not released from inquiring in case of uncertainties or from rendering professional workmanship. We recommend using a test surface first or a small area for initial, small-scale testing. Naturally, it is not possible to describe or foresee all possible current and future uses and peculiarities.

Information that is assumed to be familiar to experts has been omitted.

Please observe the current, technical, national and European standards, guidelines and data sheets regarding materials, substrates and the subsequent construction. Please contact us if you have any reservations or doubt. This version is rendered invalid if a new version is released.